

**Product Summary**

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
30V	33mΩ@10V	4.0A
	43mΩ@4.5V	

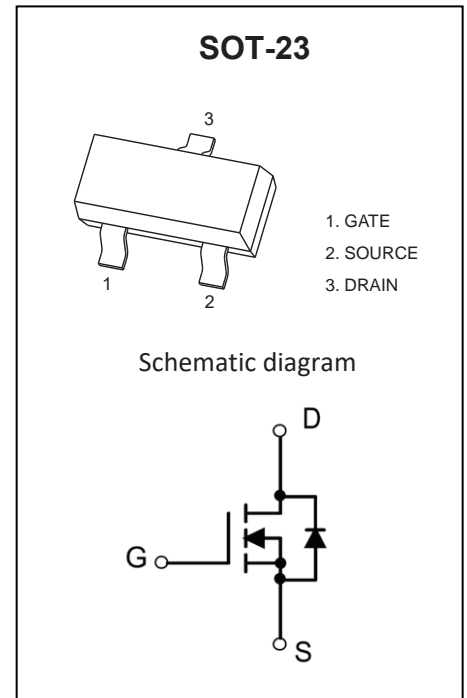
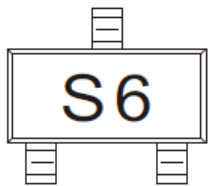
**Feature**

- TrenchFET Power MOSFET

**Application**

- Load Switch for Portable Devices
- DC/DC Converter

**MARKING:**



**ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$  unless otherwise noted)**

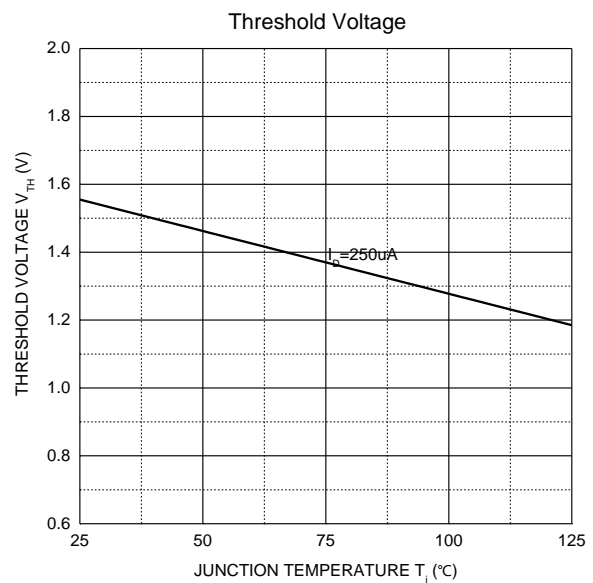
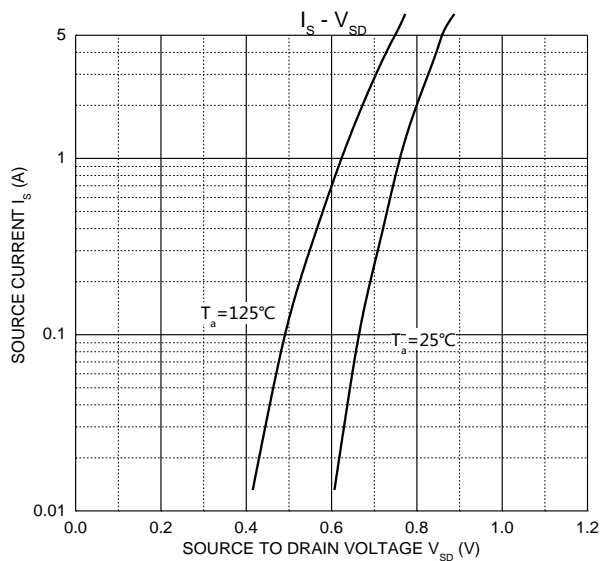
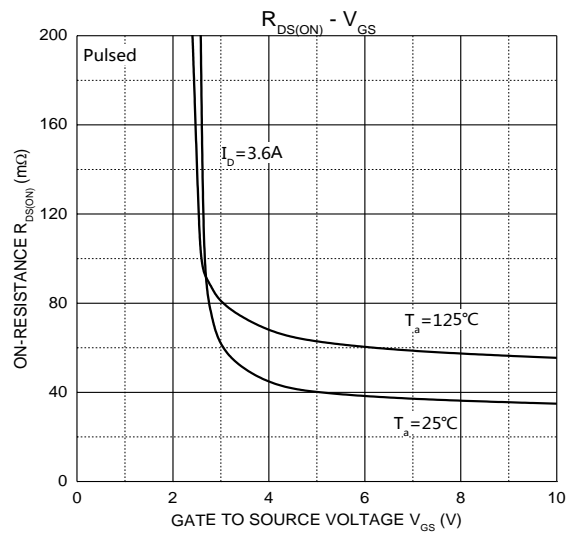
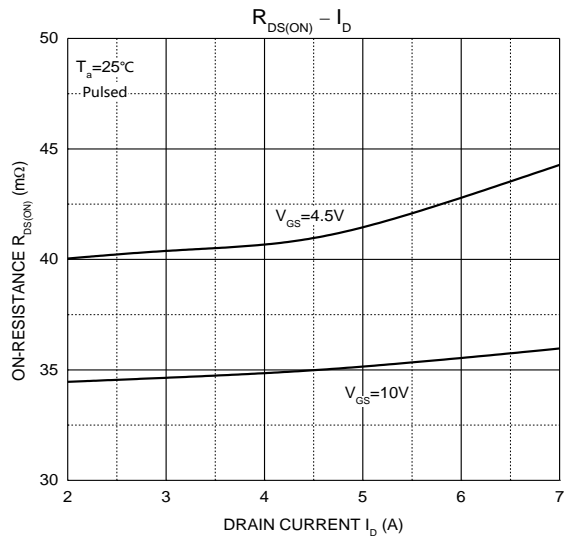
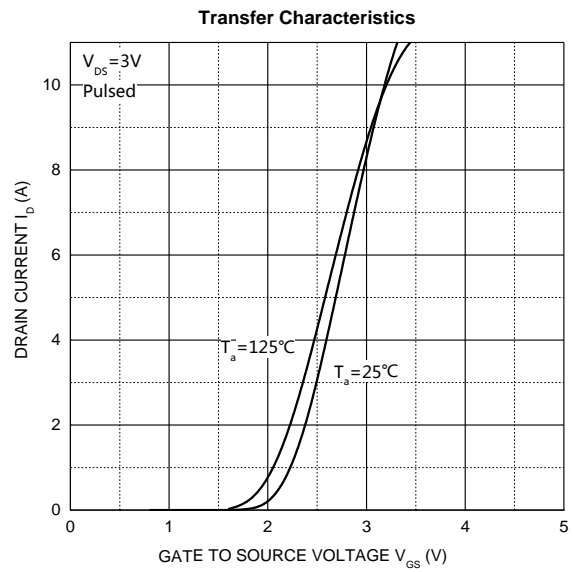
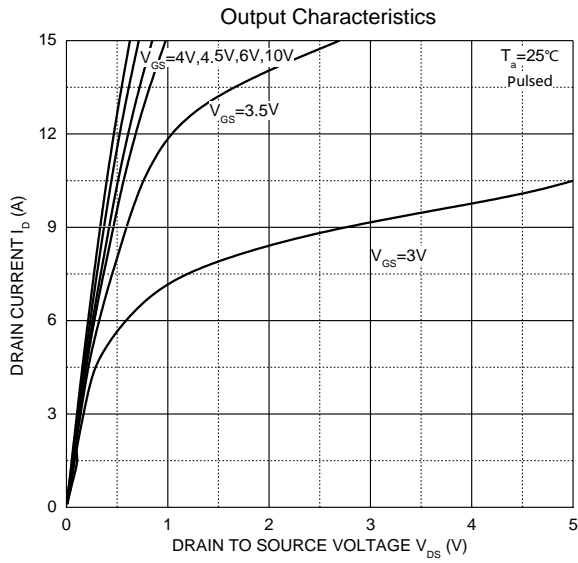
Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DS}$	30	V
Gate - Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current <sup>1,5</sup>	$I_D$	4	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	16	A
Power Dissipation <sup>4,5</sup>	$P_D$	1.5	W
Thermal Resistance from Junction to Ambient <sup>5</sup>	$R_{\theta JA}$	83.3	°C/W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~ +150	°C

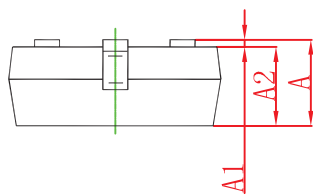
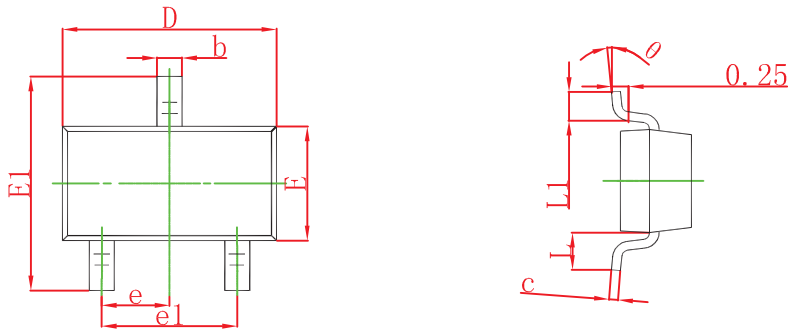
**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	30			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> = 0V			0.5	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.6	3	V
Drain-source on-resistance <sup>3</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A		33	47	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.8A		43	65	
Forward tranconductance <sup>3</sup>	g <sub>FS</sub>	V <sub>DS</sub> =4.5V, I <sub>D</sub> =2.5A		7		S
<b>Dynamic characteristics</b>						
gate charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =5V, I <sub>D</sub> =2.5A		3.0	4.5	nC
Total Gate Charge	Q <sub>gt</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =2.5A		6	9	
Gate-source charge	Q <sub>gs</sub>			1.6		
Gate-drain charge	Q <sub>gd</sub>			0.6		
Gate resistance	R <sub>g</sub>	f =1.0MHz		5	7.5	Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f =1MHz		305		pF
Output Capacitance	C <sub>oss</sub>			65		
Reverse Transfer Capacitance	C <sub>rss</sub>			29		
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, R <sub>L</sub> =15Ω, I <sub>D</sub> ≈1A, V <sub>GEN</sub> =10V, R <sub>g</sub> =6Ω		7	11	ns
Turn-on rise time	t <sub>r</sub>			12	18	
Turn-off delay time	t <sub>d(off)</sub>			14	25	
Turn-off fall time	t <sub>f</sub>			6	10	
<b>Source-Drain Diode characteristics</b>						
Body diode voltage <sup>3</sup>	V <sub>SD</sub>	I <sub>S</sub> =1.25A, V <sub>GS</sub> =0V		0.8	1.2	V

**Notes:**

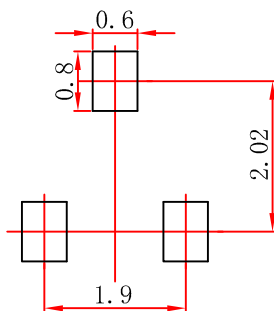
- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
- 3.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
- 4.The power dissipation P<sub>D</sub> is limited by T<sub>J(MAX)</sub> = 150°C.
- 5.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25°C.





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

### SOT-23 Suggested Pad Layout



#### Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$  mm.
3. The pad layout is for reference purposes only.